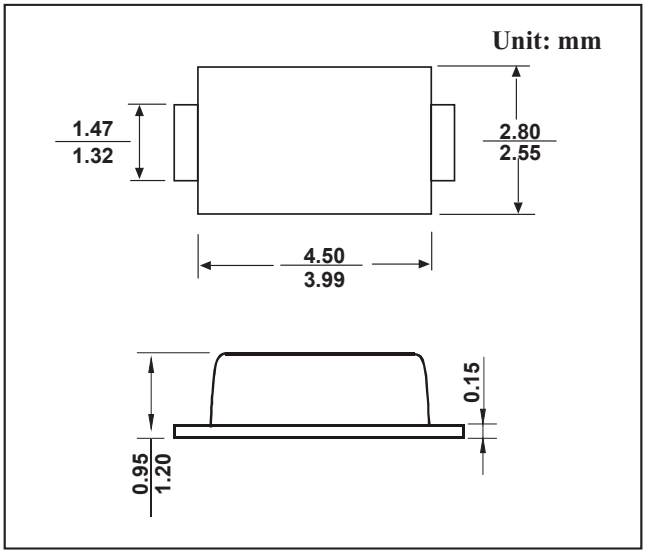
SMAF SCHOTTKY BARRIER DIODE

FEATURES

- The plastic package carries Underwrites Laboratory Flammability Classification 94V-0
- Construction utilizes void-free molded plastic technique
- High reliability
- High temperature soldering guaranteed:260 ℃/10 seconds at terminals
- Component in accordance to RoHs 2015/863 and WEEE 2012/19/EU

MECHANICAL DATA

- Case style: SMAF molded plastic
- Mounting position: Any



MAXIMUM RATINGS AND CHARACTERISTICS

@ 25°C Ambient Temperature (unless otherwise noted)

Parameter	Symbols	SS32F	SS34F	SS34AF	SS36F	SS38F	SS310F	SS312F	SS315F	SS320F	Units
Maximum Repetitive Peak Reverse Voltage	V_{RRM}	20	40	45	60	80	100	120	150	200	V
Maximum RMS voltage	V_{RMS}	14	28	31.5	42	56	70	84	105	140	V
Maximum DC Blocking Voltage	V_{DC}	20	40	45	60	80	100	120	150	200	V
Maximum Average Forward Rectified Current	$I_{F(AV)}$	3.0									A
Peak Forward Surge Current,8.3ms Single Half Sine-wave Superimposed on Rated Load (JEDEC method)	I_{FSM}	80					70				A
Max Instantaneous Forward Voltage at 3 A	V_F	0.55		0.70			0.85		0.95		V
Maximum DC Reverse Current T_a = 25°C at Rated DC Reverse Voltage T_a =100°C	I_R	0.5 10				0.3 5					mA
Typical Junction Capacitance	C_j	250				160					pF
Typical Thermal Resistance	$R_{\theta JA}$ $R_{\theta JC}$	40									°C/W
Operating Junction Temperature Range	T_j	-55 ~ +125									°C
Storage Temperature Range	T_{stg}	-55 ~ +150									°C

RATINGS AND CHARACTERISTIC CURVES

Fig.1 Forward Current Derating Curve

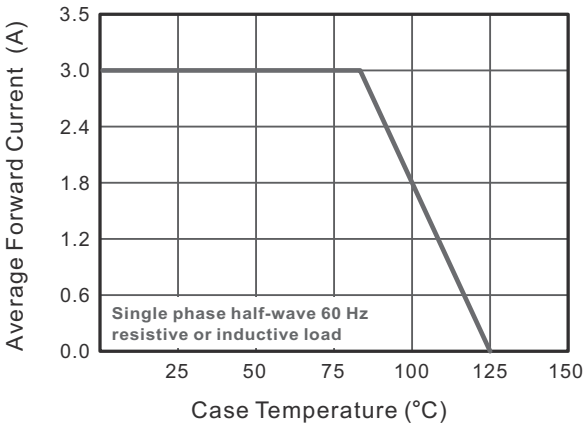


Fig.2 Typical Reverse Characteristics

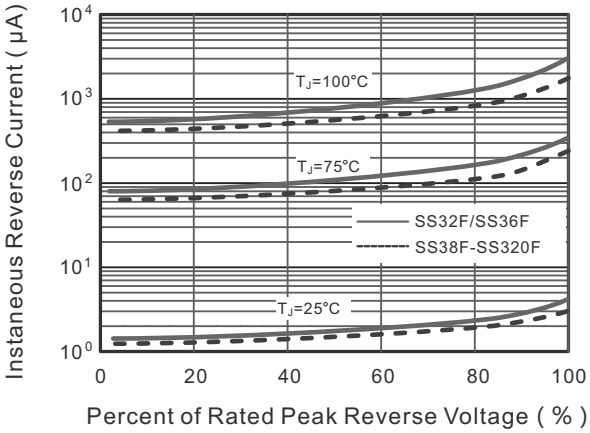


Fig.3 Typical Forward Characteristic

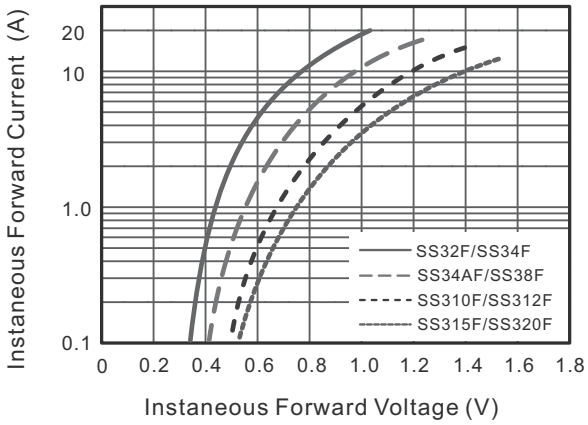


Fig.4 Typical Junction Capacitance

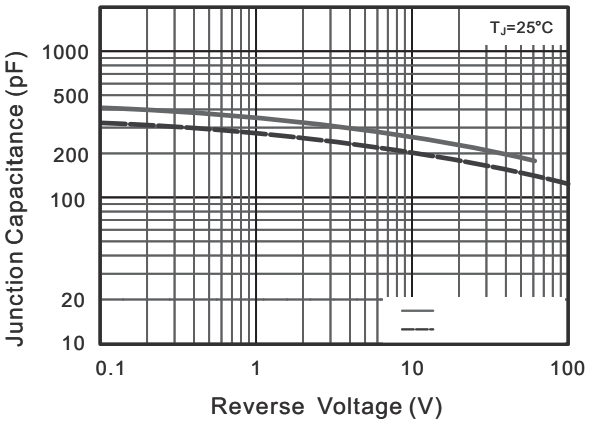


Fig.5 Maximum Non-Repetitive Peak Forward Surage Current

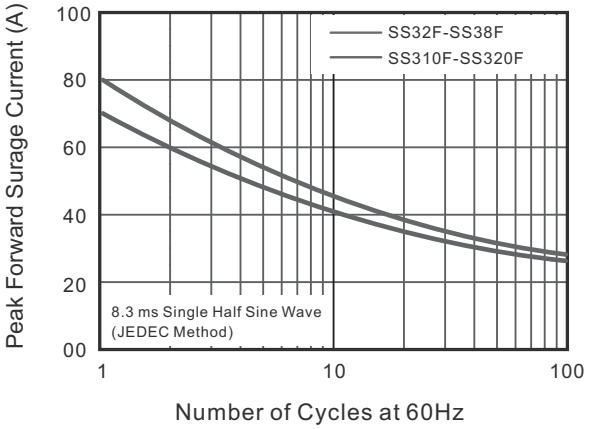


Fig.5- Typical Transient Thermal Impedance